

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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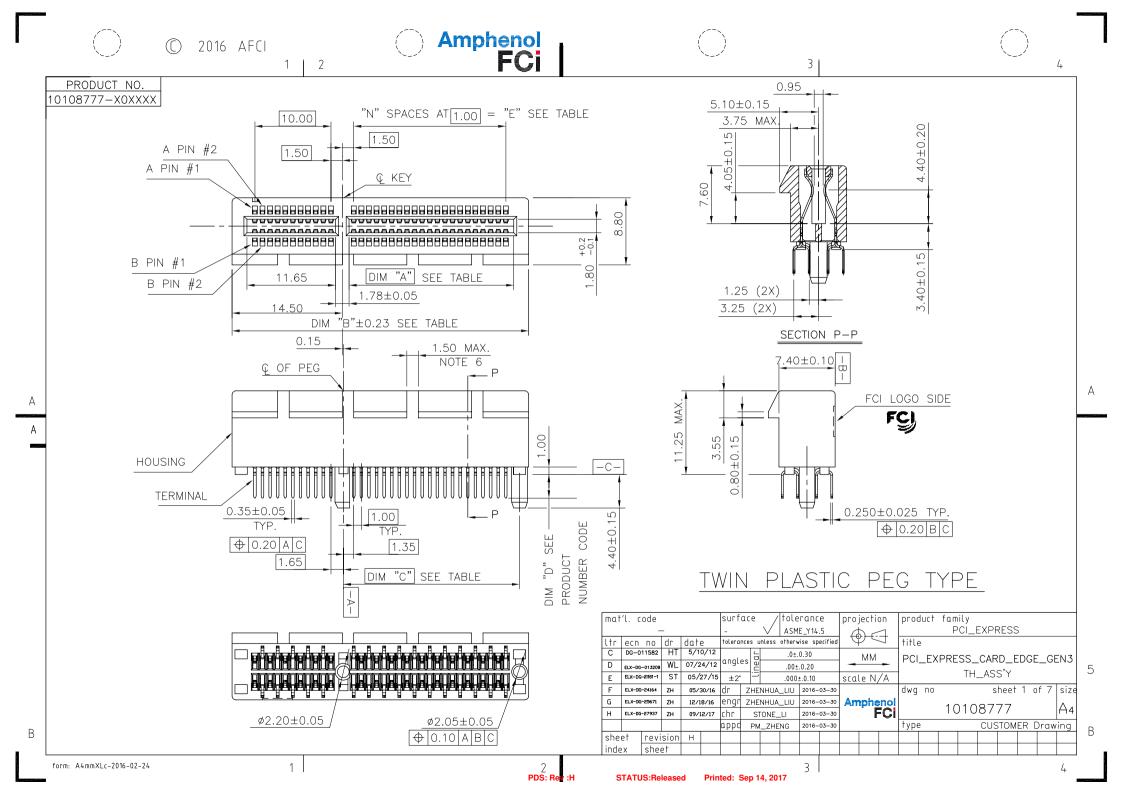
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

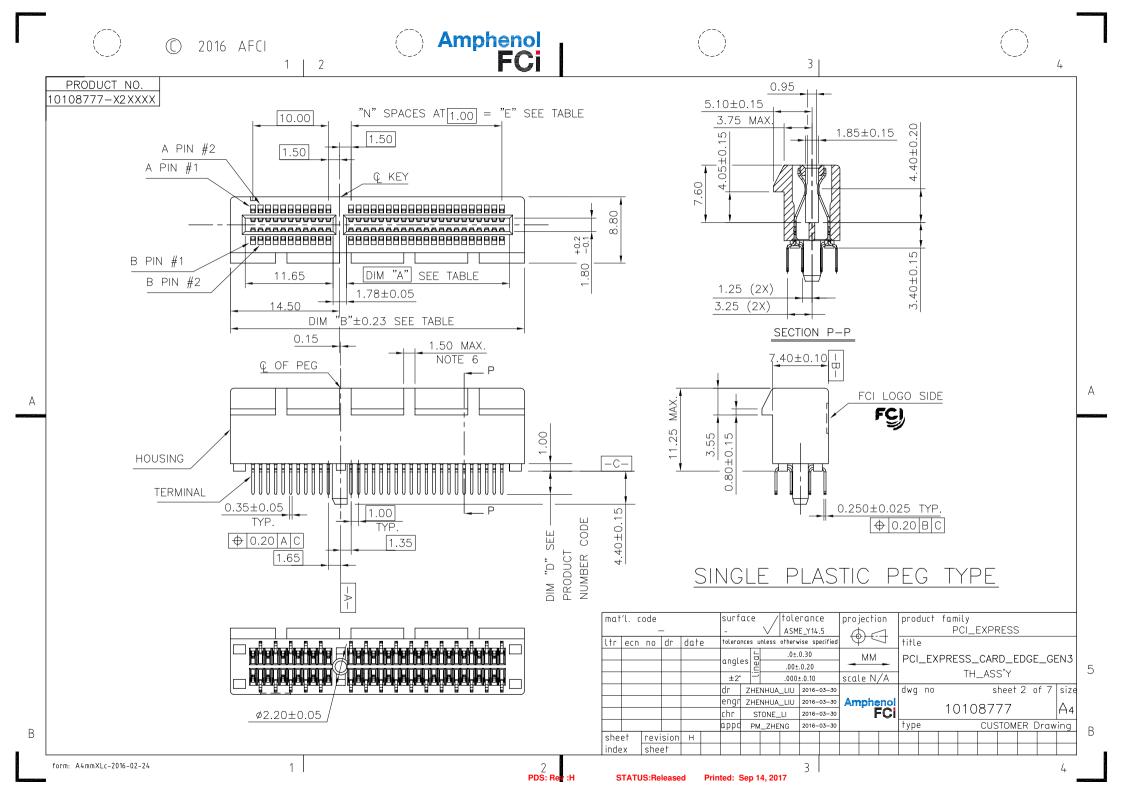
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

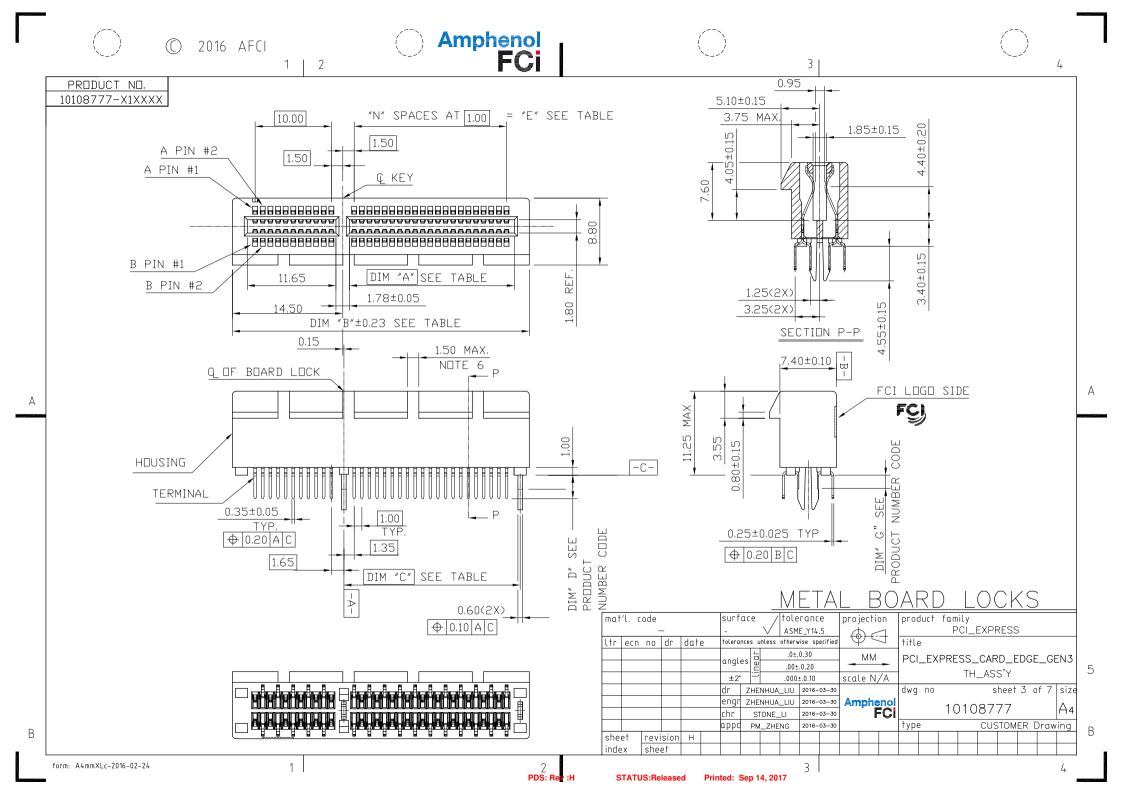


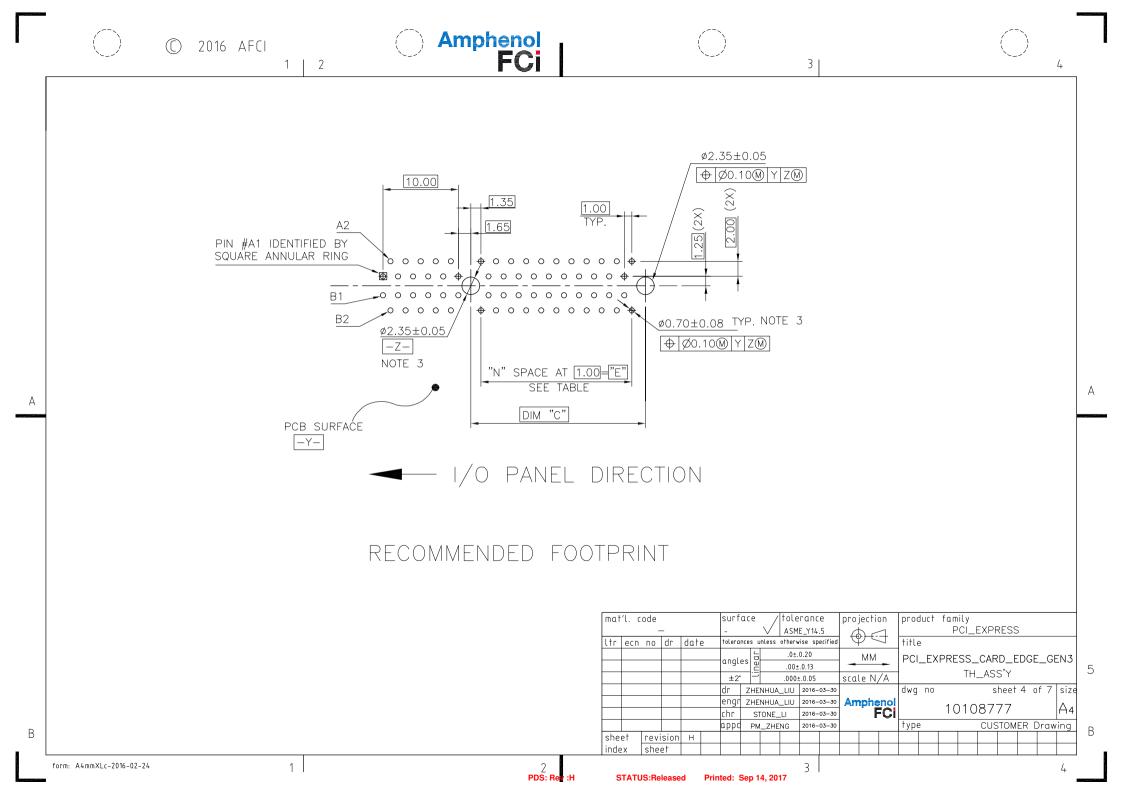


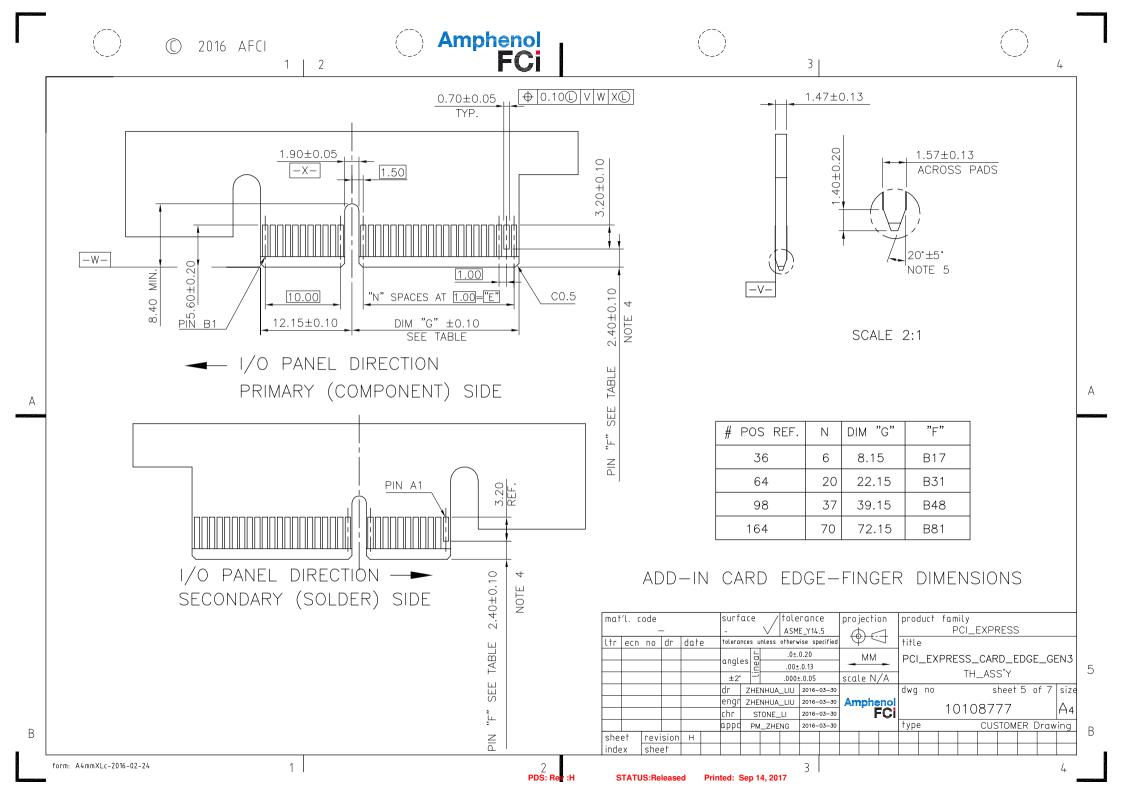












NOTES:

1.MATERIAL:

HOUSING: HIGH TEMPERATURE NYLON, GLASS FILLED UL94V-O RATED.

TERMINAL: COPPER ALLOY.

PLATING: 50u" NICKEL UNDERPLATE ALL OVER

CONTACT AREA PLATING - SEE PRODUCT NUMBER CODE SOLDER TAIL: TIN OR TIN /LEAD(90/10)- SEE PRODUCT NUMBER CODE 100u" MIN. OVER 50u" NICKEL.

METAL BOARD LOCKS: COPPER ALLOY.

FINISH: 100u" TIN OR TIN/LEAD(90/10) OVER 50u" NICKEL

UNDERPLATE SEE PRODUCT NUMBER CODE.

2.PRODUCT SPECIFICATION: GS-12-233.

(3)THE HORIZONTAL AXIS FOR THE HOLE PATTERN IS ESTABLISHED BY

A LINE THROUGH THE CENTER OF THE TWO Ø2.35 HOLES.

THE VERTICAL AXIS IS 90° TO THE HORIZONTAL AXIS, THROUGH THE CENTER

(4)NO TIE BAR PERMITTED FROM CARD EDGE TO LEADING EDGE OF PAD FOR PINS A1 AND PIN NUMBERS "F". 8.AN ADEQUATE PROCEDURE SET FORTH IN THE FOLLOWING ENSURE THAT THE PRODUCT

LEAD FREE OPTION

LEAVE BLANK FOR TERMINAL PLATING 3.4.5

"LF" FOR TERMINAL PLATING OPTION 0,1,2

POS OPTIONS

0 - 36

1 - 64

2-98 3 - 164

TAIL LENGTH OPTIONS

PCB THICKNESS DIM "G"

1.70±0.15

 2.50 ± 0.15

 1.70 ± 0.15

1.70±0.15

 1.70 ± 0.15

1.56±0.10

 2.36 ± 0.10

 1.56 ± 0.10

 1.56 ± 0.10

 2.0 ± 0.10

DIM "D"

2.30 +0.25

 $3.10^{+0.25}_{-0.13}$

 2.54 ± 0.25

1.90±0.25

3.10 +0.25

(5) CHAMFER EDGES MUST BE FREE OF CUTTING BURRS.

(6) FREQUENCY & LOCATION AT SUPPLIER DISCRETION, RIDGE MAY BE CONTINUOUS WITH NO BREAKS. 7.RoHS COMPATIBLE PRODUCT SPECIFICATIONS:

a - PLATING:

- "LF" MEANS THE PRODUCT IS LEAD-FREE, 2um MINIMUM MATTE TIN OVER 1.27um MINIMUM NICKEL UNDERPLATE.

b - MANUFACTURING PROCESS COMPATIBILITY:

- THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C±5°C TEMPERATURE FOR 10 SECONDS IN RE-FLOW APPLICATION, SEE NOTE 8 FOR APPLICATION.

PRODUCT NUMBER CODE

10108777 -x x x x x x x 🗆 🗆 HOUSING COLOR OPTIONS

0-NATURAL

1-BLACK

PEGS OPTIONS

0-PLASTIC PEGS, DIM 1-METAL BOARD LOCKS 2-SINGLE PLASTIC PEGS

TERMINAL PLATING OPTIONS

0-50u" Ni UNDERPLATE 30u" Au CONTACT AREA

100u" TIN TAIL AREA ---- COMPATIBLE ROHS

1-50u" Ni UNDERPLATE

15u" Au CONTACT AREA 100u" TIN TAIL AREA ---- COMPATIBLE RoHS

2-50u" Ni UNDERPLATE GOLD FLASH CONTACT AREA

100u" TIN TAIL AREA ---- COMPATIBLE RoHS

3-50u" Ni UNDERPLATE 30u" Au CONTACT AREA

100u" TIN/LEAD TAIL AREA --- INCOMPLIANT ROHS 4-50u" Ni UNDERPLATE

15u" Au CONTACT AREA

100u" TIN/LEAD TAIL AREA --- INCOMPLIANT RoHS

5-50u" Ni ÚNDERPLATE GOLD FLASH CONTACT AREA

100u" TIN/LEAD TAIL AREA --- INCOMPLIANT RoHS

	CONNECTOR	# POS REF.	Ν	DIM "A"	DIM "B"	DIM "C"	"E"	
	1 PORT	36	6	7.65	25.00	9.15	6.00	
	4 PORT	64	20	21.65	39.00	23.15	20.00	
8 PORT		98	37	38.65	56.00	40.15	37.00	
		164	70	71.65	89.00	73.15	70.00	

RELIABILITY CAN BE ACHIEVED DURING AND AFTER PCB ASSEMBLY OPERATION.

8.1IF PARTIAL LOT ARE USED, THE REMAINING CONNECTORS MUST BE RESEALED AND PLACED IN SAFE STORAGE WITHIN SIX HOURS OF BAG OPENING.

8.2THE SAFE STORAGE CONDITION IS RECOMMENDED AT 25°C, 40%RH.

8.3NOT FOLLOWING THE PROCEDURE MAY CAUSE BLISTER DAMAGE DURING RE-FLOW PROCESS.

8.4IF BAKING IS REQUIRED, CONNECTOR SHALL BE BAKED FOR 4 HOURS AT 125°C.

8.5REFERENCE SPECIFICATION: IPC/JEDEC J-STD-033A.

PACKAGING OPTIONS

AY WITH MYLAR FOR VACUUM PACKAGING (FOR 164P ONLY) T-SOFT TRAY PACKAGING

C-SOFT TRAY PACKAGING WITH 10MM CAP

M-SOFT TRAY PACKAGING & MYLAR TAPE, SEE FIGULE 1

Y-HARD TRAY PACKAGING (FOR 36P.98P AND 164P ONLY)

Z-HARD TRAY PACKAGING WITH MYLAR (FOR 36P,98P AND 164P ONLY)

H-SMALLER HARD TRAY PACKAGING WITH 30MM CAP (323X136X17.7 FOR 164P ONLY)

/H\Q-SMALLER HARD TRAY PACKAGING (323X136X17.7 FOR 164P ONLY)

W-TAPE & REEL PACKAGING WITHOUT MYLAR

(FOR 98P ONLY), WITH 18.0MM CAVITY WIDTH

(FOR 36, 64, 98P ONLY)

F-HARD	TRA

R-TAPE & REFL PACKAGING WITHOUT MYLAR (FOR 34, 64, 98P ONLY)

A-TAPE & REEL PACKAGING WITH MYLAR

mat'l. code						surface / tolerance					pro	jectio	ion product family										
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form: A4mmXLc-2016-02-24

PDS: Rev :H

STATUS:Released Printed: Sep 14, 2017

